



**Statement of Materials, Construction**

20L-SOICW -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.15709	Cu	7440-50-8	0.15303	28.26541	97.413
				Fe	7439-89-6	0.00369	0.68188	2.35
				Pb	7439-92-1	0.00004	0.00900	0.03
				P	7723-14-0	0.00013	0.02394	0.0825
				Zn	7440-66-6	0.00020	0.03627	0.125
2	Die	Silicon Chip	0.00344	Si	7440-21-3	0.00342	0.63222	99.5
3	Die attach material	Conductive Epoxy	0.00235	Epoxy resin	Proprietary	0.00035	0.06511	15
				Silver	7440-22-4	0.00187	0.34508	79.5
				Aromatic Amine	Proprietary	0.00013	0.02387	5.5
4	Wire	Gold	0.00120	Au	7440-57-5	0.00120	0.22163	99.99
4	Lead Finish	Alloy	0.00631	Pb	7439-92-1	0.00063	0.11655	10
				Sn	7440-31-5	0.00568	1.04897	90
6	Encapsulation	Epoxy Resin	0.37100	Fused Silica	60676-86-0	0.31424	58.04263	84.7
				Epoxy resin	29690-82-2	0.02412	4.45428	6.5
				Phenol Resin	9003-35-4	0.01484	2.74109	4
				Brominated Epoxy Resin	40039-93-8	0.00928	1.71318	2.5
				Carbon Black	1333-86-4	0.00111	0.20558	0.3
				Antimony trioxide	1309-64-4	0.00742	1.37055	2
Total Package weight			0.54139					

**Note:** Component Weight based on assembly of generic parts.